

March 2008

# **NC7SZ126**

# TinyLogic® UHS Buffer with 3-STATE Output

#### **Features**

- Space saving SOT23 or SC70 5-lead package
- Ultra small MicroPak™ leadless package
- Ultra High Speed; t<sub>PD</sub> 2.6ns Typ. into 50pF at 5V V<sub>CC</sub>
- High Output Drive; ±24mA at 3V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range; 1.65V to 5.5V
- $\blacksquare$  Matches the performance of LCX when operated at 3.3V  $V_{CC}$
- Power down high impedance inputs/output
- Overvoltage tolerant inputs facilitate 5V to 3V translation
- Patented noise/EMI reduction circuitry implemented

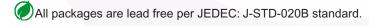
## **General Description**

The NC7SZ126 is a single buffer with 3-STATE output from Fairchild's Ultra High Speed Series of TinyLogic  $^{\tiny (8)}$ . The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad  $V_{CC}$  operating range. The device is specified to operate over the 1.65V to 5.5V range. The inputs and output are high impedance above ground when  $V_{CC}$  is 0V. Inputs tolerate voltages up to 6V independent of  $V_{CC}$  operating voltage. The output tolerates voltages above  $V_{CC}$  in the 3-STATE condition.

## **Ordering Information**

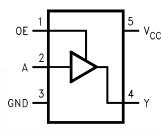
Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7SZ126M5X	MA05B	7Z26	5-Lead SOT23, JEDEC MO-178, 1.6mm	3k Units on Tape and Reel
NC7SZ126P5X	MAA05A	Z26	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3k Units on Tape and Reel
NC7SZ126L6X	MAC06A	FF	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



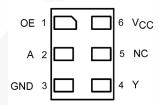
# **Connection Diagram**

Pin Assignments for SC70 and SOT23



(Top View)

#### Pad Assignments for MicroPak



(Top Thru View)

# **Pin Description**

Pin Names	Description
A, OE	Inputs
Υ	Output
NC	No Connect

# **Logic Symbol**



## **Function Table**

Inp	Inputs					
OE	Α	OUTY				
Н	L	L				
Н	Н	Н				
L	Х	Z				

H = HIGH Logic Level

L = LOW Logic Level

X = HIGH or LOW Logic Level

Z = HIGH Impedance State

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	-0.5V to +6V
V <sub>IN</sub>	DC Input Voltage	-0.5V to +6V
V <sub>OUT</sub>	DC Output Voltage	-0.5V to +6V
I <sub>IK</sub>	DC Input Diode Current @ V <sub>IN</sub> < -0.5V @ V <sub>IN</sub> > 6V	–50mA +20mA
ІОК	DC Output Diode Current  @ V <sub>OUT</sub> < -0.5V  @ V <sub>OUT</sub> > 6V, V <sub>CC</sub> = GND	–50mA +20mA
I <sub>OUT</sub>	DC Output Current	±50mA
I <sub>CC</sub> /I <sub>GND</sub>	DC V <sub>CC</sub> /GND Current	±50mA
T <sub>STG</sub>	Storage Temperature	-65°C to +150°C
T <sub>J</sub>	Junction Temperature under Bias	150°C
T <sub>L</sub>	Junction Lead Temperature (Soldering, 10 seconds)	260°C
P <sub>D</sub>	Power Dissipation @ +85°C SOT23-5 SC70-5	200mW 150mW

# Recommended Operating Conditions<sup>(1)</sup>

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage Operation	1.65V to 5.5V
V <sub>CC</sub>	Supply Voltage Data Retention	1.5V to 5.5V
V <sub>IN</sub>	Input Voltage	0V to 5.5V
V <sub>OUT</sub>	Output Voltage Active State 3-STATE	0V to V <sub>CC</sub> 0V to 5.5V
T <sub>A</sub>	Operating Temperature	-40°C to +85°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC} = 1.8V, 2.5V \pm 0.2V$ $V_{CC} = 3.3V \pm 0.3V$ $V_{CC} = 5.0V \pm 0.5V$	0ns/V to 20ns/V 0ns/V to 10ns/V 0ns/V to 5ns/V
$\theta_{JA}$	Thermal Resistance SOT23-5 SC70-5	300°C/W 425°C/W

#### Notes:

1. Unused inputs must be held HIGH or LOW. They may not float.

# **DC Electrical Characteristics**

					T <sub>A</sub> = +25°C			$T_A = -40^{\circ}C$		
Symbol	mbol Parameter V <sub>CC</sub> (V) Conditions		Min.	Тур.	Max.	Min.	Max.	Unit		
V <sub>IH</sub>	HIGH Level	1.65–1.95			0.75 x V <sub>CC</sub>			0.75 x V <sub>CC</sub>		V
	Input Voltage	2.3–5.5			0.7 x V <sub>CC</sub>			0.7 x V <sub>CC</sub>		
V <sub>IL</sub>	LOW Level Input	1.65–1.95					0.25 x V <sub>CC</sub>		0.25 x V <sub>CC</sub>	V
	Voltage	2.3-5.5					0.3 x V <sub>CC</sub>		0.3 x V <sub>CC</sub>	
V <sub>OH</sub>	HIGH Level	1.65	$V_{IN} = V_{IH}$	$I_{OH} = -100\mu A$	1.55	1.65		1.55		V
	Output Voltage	1.8			1.7	1.8		1.7		
		2.3			2.2	2.3		2.2		
		3.0			2.9	3.0		2.9		
		4.5			4.4	4.5		4.4		
		1.65		$I_{OH} = -4mA$	1.29	1.52		1.29		
		2.3		$I_{OH} = -8mA$	1.9	2.15		1.9		
		3.0		$I_{OH} = -16mA$	2.4	2.80		2.4		
		3.0		$I_{OH} = -24mA$	2.3	2.68		2.3		
		4.5		$I_{OH} = -32mA$	3.8	4.20		3.8		
V <sub>OL</sub>	LOW Level	1.65	$V_{IN} = V_{IL}$	I <sub>OL</sub> = 100μA		0.0	0.1		0.1	V
	Output Voltage	1.8				0.0	0.1		0.1	
		2.3				0.0	0.1		0.1	
		3.0				0.0	0.1		0.1	
		4.5				0.0	0.1		0.1	
		1.65		I <sub>OL</sub> = 4mA		0.08	0.24		0.24	
		2.3		I <sub>OL</sub> = 8mA		0.10	0.3		0.3	
		3.0		I <sub>OL</sub> = 16mA		0.15	0.4		0.4	
		3.0		I <sub>OL</sub> = 24mA		0.22	0.55		0.55	
		4.5		$I_{OL} = 32mA$		0.22	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	0–5.5	V <sub>IN</sub> = 5.5\	, GND			±1		±10	μA
I <sub>OZ</sub>	3-STATE Output Leakage	0–5.5	$V_{IN} = V_{IH}$ $V_{O} = V_{CC}$	or V <sub>IL</sub> , or GND			±1		±10	μA
I <sub>OFF</sub>	Power Off Leakage Current	0.0	V <sub>IN</sub> or V <sub>Ol</sub>	<sub>T</sub> = 5.5V			1		10	μA
I <sub>CC</sub>	Quiescent Supply Current	1.65–5.5	V <sub>IN</sub> = 5.5\	/, GND			2.0		20	μA

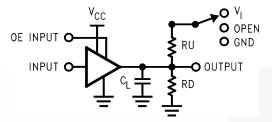
## **AC Electrical Characteristics**

				T,	λ = <b>+25</b>	°C		–40°C 85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	Fig. No.
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation	1.65	$C_L = 15pF, RD = 1M\Omega,$	2.0	6.4	13.2	2.0	13.8	ns	Figure 1
	Delay	1.8	S <sub>1</sub> = OPEN	2	5.3	11	2	11.5		Figure 3
		2.5 ± 0.2		0.8	3.4	7.5	0.8	8.0		
		3.3 ± 0.3		0.5	2.5	5.2	0.5	5.5		
		5.0 ± 0.5		0.5	2.1	4.5	0.5	4.8		
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation	3.3 ± 0.3	$C_L = 50 pF$ , $RD = 500 \Omega$ ,	1.5	3.2	5.7	1.5	6.0	ns	Figure 1
	Delay	5.0 ± 0.5	S <sub>1</sub> = OPEN	0.8	2.6	5.0	0.8	5.3		Figure 3
t <sub>PZL</sub> , t <sub>PZH</sub>	Output Enable	1.65	$C_L = 50 pF$ , $RD = 500 \Omega$ ,	2.0	8.4	15.0	2.0	15.6	ns	Figure 1
	Time	1.8	RU = 500Ω, S <sub>1</sub> = GND for $t_{PZH}$ ,	2.0	6.1	11.5	2	12		Figure 3
		2.5 ± 0.2	$S_1 = S_1 = S_1$ for $t_{PZL}$ ,	1.5	3.8	8.0	1.5	8.5		
		3.3 ± 0.3	$V_1 = 2 \times V_{CC}$	1.5	3.2	5.7	1.5	6.0		
		5.0 ± 0.5		0.8	2.3	5.0	0.8	5.3		
t <sub>PLZ</sub> , t <sub>PHZ</sub>	Output Disable	1.65	$C_L = 50 \text{ pF}, \text{ RD} = 500\Omega,$	2.0	6.5	13.2	2.0	14.5	Fi	Figure 1
	Time	1.8	RU = 500Ω, S <sub>1</sub> = GND for $t_{PHZ}$ ,	2.0	5.6	11	2.0	12		Figure 3
		2.5 ± 0.2	$S_1 = S_1 = S_1$ for $t_{PLZ}$ ,	1.0	4.0	8.0	1.0	8.5		
		3.3 ± 0.3	$V_1 = 2 \times V_{CC}$	1.0	3.5	5.7	1.0	6.0		
		5.0 ± 0.5		0.5	2.5	4.7	0.5	5.0		
C <sub>IN</sub>	Input Capacitance	0			4				pF	
C <sub>OUT</sub>	Output Capacitance	0			8				pF	
C <sub>PD</sub>	Power Dissipation	3.3	(2)		17				pF	Figure 2
	Capacitance	5.0			24					

### Note:

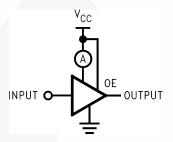
2.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption ( $I_{CCD}$ ) at no output loading and operating at 50% duty cycle. (See Figure 2.)  $C_{PD}$  is related to  $I_{CCD}$  dynamic operating current by the expression:  $I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC} \text{ static})$ .

# **AC Loading and Waveforms**



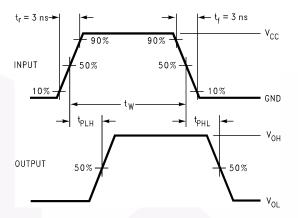
 $C_L$  includes load and stray capacitance Input PRR = 1.0MHz,  $t_{\rm W} = 500 {\rm ns}$ 

Figure 1. AC Test Circuit



Input = AC Waveform;  $t_r = t_f = 1.8$ ns; PRR = 10MHz; Duty Cycle = 50%

Figure 2. I<sub>CCD</sub> Test Circuit



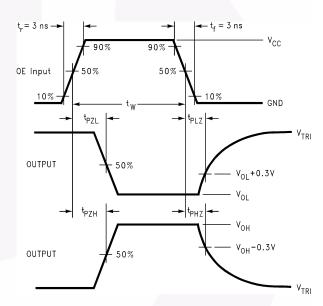


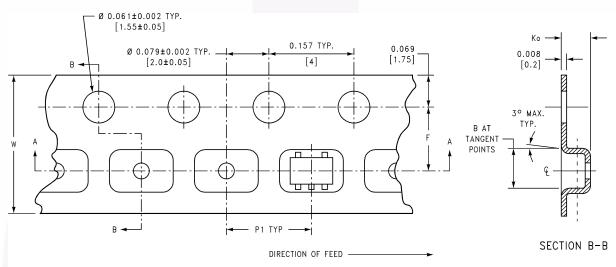
Figure 3. AC Waveforms

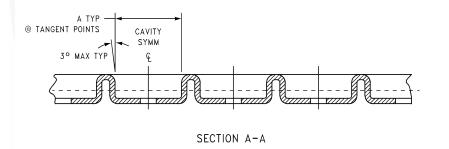
# **Tape and Reel Specifications**

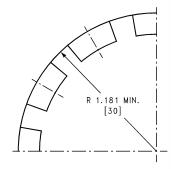
## Tape Format for SC70 and SOT23

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
M5X, P5X	Leader (Start End)	125 (typ.)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ.)	Empty	Sealed

## Tape Dimensions inches (millimeters)







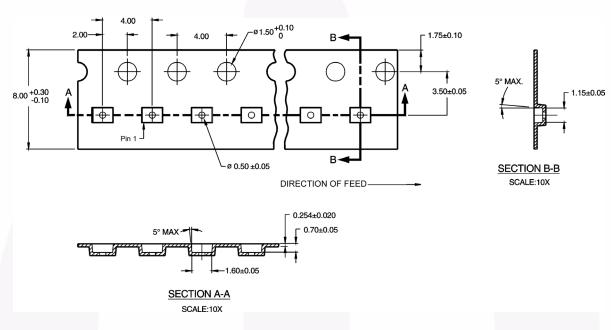
BEND RADIUS NOT TO SCALE

Package	Tape Size	Dim A	Dim B	Dim F	Dim K <sub>o</sub>	Dim P1	Dim W
SC70-5	8mm	0.093 (2.35)	0.096 (2.45)	0.138 ± 0.004 (3.5 ± 0.10)	0.053 ± 0.004 (1.35 ± 0.10)	0.157 (4)	0.315 ± 0.004 (8 ± 0.1)
SOT23-5	8mm	0.130 (3.3)	0.130 (3.3)	0.138 ± 0.002 (3.5 ± 0.05)	0.055 ± 0.004 (1.4 ± 0.11)	0.157 (4)	0.315 ± 0.012 (8 ± 0.3)

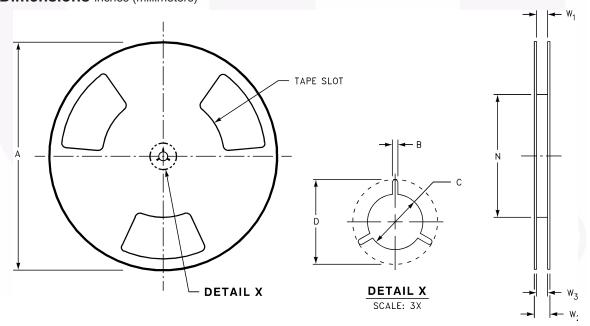
# Tape and Reel Specifications (Continued)

## **Tape Format for MicroPak**

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L6X	Leader (Start End)	125 (typ.)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (typ.)	Empty	Sealed



# Reel Dimensions inches (millimeters)



Tape Size	Α	В	С	D	N	W1	W2	W3
8 mm	7.0	0.059	0.512	0.795	2.165	0.331 + 0.059/-0.000	0.567	W1 + 0.078/–0.039
	(177.8)	(1.50)	(13.00)	(20.20)	(55.00)	(8.40 + 1.50/–0.00)	(14.40)	(W1 + 2.00/–1.00)

# **Physical Dimensions** 3.00 2.80 Α В 3.00 2.60 1.70 1.50 2.60 (0.30)0.50 0.30 1.00 0.95 ⊕ 0.20(M) C A B 1.90 0.70 **TOP VIEW** LAND PATTERN RECOMMENDATION SEE DETAIL A 1.30 1.45 MAX 0.90 0.15 0.05 0.22 C 0.08 ○ 0.10 C NOTES: UNLESS OTHEWISE SPECIFIED A) THIS PACKAGE CONFORMS TO JEDEC MO-178, ISSUE B, VARIATION AA, B) ALL DIMENSIONS ARE IN MILLIMETERS. GAGE PLANE C) MA05Brev5 0.25

Figure 4. 5-Lead SOT23, JEDEC MO-178, 1.6mm

SEATING PLANE

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0.55 0.35

0.60 REF

# Physical Dimensions (Continued) **SYMM** E 2.00±0.20-0.65 0.50 MIN 1.25±0.10 1.90 3 (0.25)-0.40 MIN 1.30 ⊕ 0.10M A B 0.65 LAND PATTERN RECOMMENDATION 1.30 SEE DETAIL A 1.00 0.80 0.10 0.10 $2.10\pm0.30$ SEATING PLANE GAGE PLANE NOTES: UNLESS OTHERWISE SPECIFIED (R0.10) THIS PACKAGE CONFORMS TO EIAJ SC-88A, 1996. B) C) ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. 0.20 DETAIL A

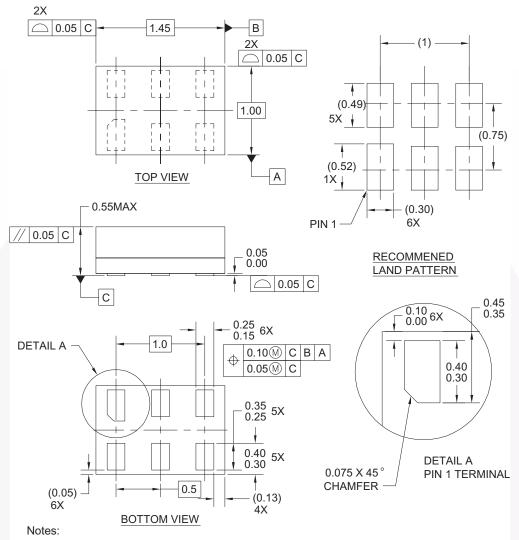
Figure 5. 5-Lead SC70, EIAJ SC-88a, 1.25mm Wide

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MAA05AREV5

## Physical Dimensions (Continued)



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06AREVC

Figure 6. 6-Lead MicroPak, 1.0mm Wide

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MicroPak™ MillerDrive™ Motion-SPM™ OPTOLOGIC®

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev. I33

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